EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	31	("438"/$.ccls. or "257"/$.ccls.) and $3mount and (light adj emitting adj diode or LED) and metal$3 and plate and bond$3 and (therm$4 near5 conduct$5) and $5conduct$5 and fill$3 and insulat$3 and (heat same transfer$3) and (recess or groove or protrusion) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:08
L9	128	$3mount and (light adj emitting adj diode or LED) and metal$3 and plate and bond$3 and (therm$4 near5 conduct$5) and $5conduct$5 and fill$3 and insulat$3 and (heat same transfer$3) and (recess or groove or protrusion) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 17:57
L22	6	(438/22-47.ccls. or 257/79-84,88, 91,95,101-103,676,774.ccls.) and $3mount$3 and (light adj emitting adj diode or LED) and metal$3 and bond$3 and (therm$4 same conduct$5) and $5conduct$5 and fill$3 and insulat$3 and (heat same transfer$3) and (recess$3 or groove or protrusion or trench) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:14
L23	10	(438/22-47.ccls. or 257/79-84,88, 91,95,101-103,676,774.ccls.) and (light adj emitting adj diode or LED) and metal$3 and bond$3 and (therm$4 same conduct$5) and $5conduct$5 and fill$3 and insulat$3 and (heat same transfer$3) and (recess$3 or groove or protrusion or trench) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:18
L26	1	("20070007540").PN.	US-PGPUB; USPAT	OR	OFF	2007/07/15 18:15

L27	12	("20010030866"|"20040012958"|"20040190304"|"5172301"|"5825625"|"6159764"|"6498355"|"6501103"|"6506629"|"6562643"|"6874910"|"6930332").PN.	US-PGPUB; USPAT	OR	ON	2007/07/15 18:27
L28	1	("6498355").PN.	US-PGPUB; USPAT	OR	OFF	2007/07/15 18:51
L29	10	(438/22-47.ccls. or 257/79-84,88, 91,95,101-103,676,774.ccls.) and (light adj emitting adj diode or LED) and bond$3 and (therm$4 same conduct$5) and $5conduct$5 and fill$3 and insulat$3 and (heat same transfer$3) and (recess$3 or groove or protrusion or trench) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:19
L33	10	(438/22-47.ccls. or 257/79-103,676, 774.ccls.) and (light adj emitting adj diode or LED) and bond$3 and (therm$4 same conduct$5) and $5conduct$5 and fill$3 and insulat$3 and (heat same transfer$4) and (recess$3 or groov$2 or protru$4 or trench) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:58
L37	11	23 or 29 or 33	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:27
L38	37	(438/22-47.ccls. or 257/79-103,676, 774.ccls. or "361"/$.ccls. or "362"/$.ccls.) and (light adj emitting adj diode or LED) and bond$3 and (therm$4 same conduct$5) and $5conduct$5 and fill$3 and insulat$3 and (heat same transfer$4) and (recess$3 or groov$2 or protru$4 or trench) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:32

L40	16	(438/22-47.ccls. or 257/79-103,676, 774.ccls. or "361"/$.ccls. or "362"/$.ccls.) and $3mount and (light adj emitting adj diode or LED) and metal$3 and plate and bond$3 and (therm$4 near5 conduct$5) and $5conduct$5 and fill$3 and insulat$3 and (heat same transfer$3) and (recess or groove or protrusion) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:38
L41	25	37 or 40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:58
L53	16	(438/22-47.ccls. or 257/79-103,676, 774.ccls. or "361"/$.ccls. or "362"/$.ccls.) and $3mount and (light adj emitting adj diode or LED) and metal$3 and plate and bond$3 and (therm$4 near5 conduct$5) and $5conduct$5 and fill$3 and (heat same transfer$3) and (recess or groove or protrusion) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3) and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:56
L61	66	(438/22-47.ccls. or 257/79-103,676, 774.ccls. or "361"/$.ccls. or "362"/$.ccls.) and $3mount$3 and (light adj emitting adj diode or LED) and metal$3 and plat$3 and bond$3 and (therm$4 same conduct$5 or therm$4 same contact) and $5conduct$5 and fill$3 and (heat same (transfer$3 or spread$3 or dissipat$3)) and (recess$3 or groov$2 or protru$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3 or deposit$3) and die and wir$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:13

L62	399	$3mount$3 and (light adj emitting adj diode or LED) and metal$3 and plat$3 and bond$3 and (therm$4 same conduct$5 or therm$4 same contact) and $5conduct$5 and fill$3 and (heat same (transfer$3 or spread$3 or dissipat$3)) and (recess$3 or groov$2 or protru$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3 or deposit$3) and die and wir$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:57
L63	25	(438/22-47.ccls. or 257/79-103,676, 774.ccls.) and $3mount$3 and (light adj emitting adj diode or LED) and metal$3 and plat$3 and bond$3 and (therm$4 same conduct$5 or therm$4 same contact) and $5conduct$5 and fill$3 and (heat same (transfer$3 or spread$3 or dissipat$3)) and (recess$3 or groov$2 or protru$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3 or deposit$3) and die and wir$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 18:58
L64	16	41 and $3mount$3 and (light adj emitting adj diode or LED) and metal$3 and plat$3 and bond$3 and (therm$4 same conduct$5 or therm$4 same contact) and $5conduct$5 and fill$3 and (heat same (transfer$3 or spread$3 or dissipat$3)) and (recess$3 or groov$2 or protru$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3 or deposit$3) and die and wir$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:39
L65	67	53 or 61 or 63 or 64	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:00

L68	29	(438/22-47.ccls. or 257/79-103,676, 774.ccls. or 361/794,813,414.ccls. or 362/294,241,555.ccls.) and $3mount$3 and (light adj emitting adj diode or LED) and metal$3 and plat$3 and bond$3 and (therm$4 same conduct$5 or therm$4 same contact) and $5conduct$5 and fill$3 and (heat same (transfer$3 or spread$3 or dissipat$3)) and (recess$3 or groov$2 or protru$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3 or deposit$3) and die and wir$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:52
L69	26	(US-20040012958-$ or US-20020085390-$ or US-20020004251-$ or US-20030170922-$ or US-20030022407-$ or US-20010052600-$ or US-20010050370-$ or US-20060119250-$ or US-20050072981-$ or US-20030189830-$).did. or (US-6936855-$ or US-6498355-$ or US-6943433-$ or US-5311407-$ or US-6885563-$ or US-6828170-$ or US-6335548-$ or US-5311060-$ or US-6756610-$ or US-6696310-$ or US-6558970-$ or US-6534330-$ or US-6318886-$ or US-6784530-$ or US-6452217-$ or US-6706546-$).did.	US-PGPUB; USPAT	OR	ON	2007/07/15 19:23
L78	20	69 and (through adj hole or throughhole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:54
L79	18	78 and (NOT (HASHIMOTO or SUGIMOTO or YOKOTANI or NISHIOKA or IWAHORI or ISHIZAKI or SUZUKI or UCHINONO or MUTO or MORI or KIMURA).in.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:52

L86	13	(US-20020004251-$ or US-20030170922-$ or US-20030022407-$ or US-20010052600-$ or US-20010050370-$).did. or (US-6936855-$ or US-6498355-$ or US-5311407-$ or US-6885563-$ or US-6335548-$ or US-6318886-$ or US-6784530-$ or US-6706546-$).did.	US-PGPUB; USPAT	OR	ON	2007/07/15 19:46
L89	11	86 and heat and (silicon or silicone or Si)	US-PGPUB; USPAT	OR	ON	2007/07/15 19:45
L92	16	41 and $3mount$3 and (light adj emitting adj diode or LED) and metal$3 and plat$3 and bond$3 and (therm$4 same conduct$5 or therm$4 same contact) and $5conduct$5 and fill$3 and (heat same (transfer$3 or spread$3 or dissipat$3)) and (recess$3 or groov$2 or protru$4 or trench or through adj hole or throughhole) and (layer or film) and (embedd$3 or bury$3 or imbed$4 or implant$5 or inlay$3 or deposit$3) and die and wir$5 and @ad<"20030526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:52
L93	15	92 and (NOT (HASHIMOTO or SUGIMOTO or YOKOTANI or NISHIOKA or IWAHORI or ISHIZAKI or SUZUKI or UCHINONO or MUTO or MORI or KIMURA).in.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:53
L94	31	79 or 93	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:53
L95	29	94 and (through adj hole or throughhole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/15 19:54